

CoolSiC™ 1200 V SiC Trench MOSFET : Silicon Carbide MOSFET

Features

- $V_{DS} = 1200\text{ V}$ at $T_{vj} = 25^\circ\text{C}$
- $I_{DC} = 55\text{ A}$ at $T_c = 25^\circ\text{C}$
- $R_{DS(on)} = 39\text{ m}\Omega$ at $V_{GS} = 18\text{ V}$, $T_{vj} = 25^\circ\text{C}$
- Very low switching losses
- Short circuit withstand time $3\ \mu\text{s}$
- Benchmark gate threshold voltage, $V_{GS(th)} = 4.2\text{ V}$
- Robust against parasitic turn on, 0 V turn-off gate voltage can be applied
- Robust body diode for hard commutation
- .XT interconnection technology for best-in-class thermal performance

Potential applications

- Industrial drives
- Industrial power supplies
- Solar inverters

Product validation

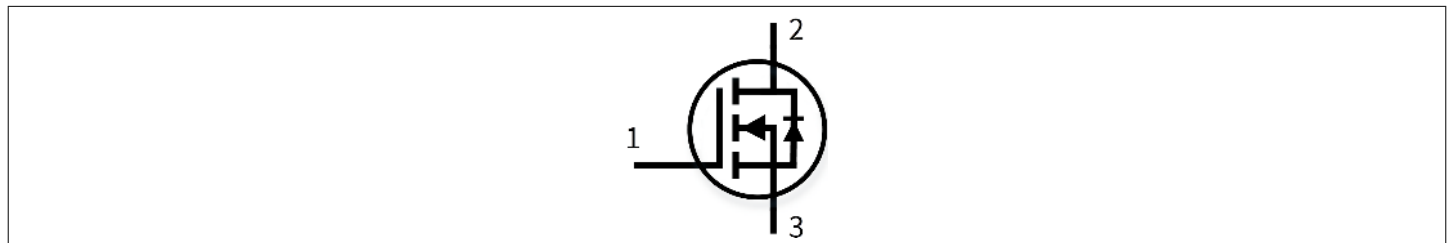
- Qualified for industrial applications according to the relevant tests of JEDEC47/20/22
- Please also note the application note AN2019-05 for power and thermal cycling



- Halogen-free
- Green
- Lead-free
- RoHS

Description

- 1 – gate
- 2 – drain
- 3 – source



Type	Package	Marking
IMW120R040M1H	PG-TO247-3-STD-NN2.5	12M1H040

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1 Package

Table 1 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Storage temperature	T_{stg}		-55		150	°C
Soldering temperature	T_{sold}	wave soldering 1.6 mm (0.063 in.) from case for 10 s			260	°C
Mounting torque	M	M3 screw, Maximum of mounting processes: 3			0.6	Nm
Thermal resistance, junction-ambient	$R_{th(j-a)}$				62	K/W
MOSFET/body diode thermal resistance, junction-case	$R_{th(j-c)}$			0.51	0.66	K/W

2 MOSFET

Table 2 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit	
Drain-source voltage	V_{DSS}	$T_{vj} \geq 25\text{ °C}$	1200	V	
Continuous DC drain current for $R_{th(j-c,max)}$, limited by $T_{vj(max)}$	I_{DDC}	$V_{GS} = 18\text{ V}$	$T_c = 25\text{ °C}$	55	A
			$T_c = 100\text{ °C}$	39	
Peak drain current, t_p limited by $T_{vj(max)}$	I_{DM}	$V_{GS} = 18\text{ V}$	117	A	
Gate-source voltage, max. transient voltage ¹⁾	V_{GS}	$t_p \leq 0.5\text{ }\mu\text{s}$, $D < 0.01$	-10/23	V	
Gate-source voltage, max. static voltage	V_{GS}		-7/20	V	
Avalanche energy, single pulse	E_{AS}	$I_D = 18.8\text{ A}$, $V_{DD} = 50\text{ V}$, $L = 1.9\text{ mH}$	339	mJ	
Avalanche energy, repetitive	E_{AR}	$I_D = 18.8\text{ A}$, $V_{DD} = 50\text{ V}$, $L = 9.5\text{ }\mu\text{H}$	1.68	mJ	
Short-circuit withstand time	t_{SC}	$V_{DD} \leq 800\text{ V}$, $V_{DS,peak} < 1200\text{ V}$, $V_{GS(on)} = 15\text{ V}$, $T_{vj(start)} = 25\text{ °C}$	3	μs	
MOSFET dv/dt robustness	dv/dt	$V_{DS} = 0\dots 800\text{ V}$	150	V/ns	
Power dissipation, limited by $T_{vj(max)}$	P_{tot}		$T_c = 25\text{ °C}$	227	W
			$T_c = 100\text{ °C}$	114	

1) Important note: The selection of positive and negative gate-source voltages impacts the long-term behavior of the device. The design guidelines described in Application Note AN2018-09 must be considered to ensure sound operation of the device over the planned lifetime.

Table 3 Recommended values

Parameter	Symbol	Note or test condition	Values	Unit
Recommended turn-on gate voltage	$V_{GS(on)}$		15...18	V
Recommended turn-off gate voltage	$V_{GS(off)}$		-5...0	V

Table 4 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit	
			Min.	Typ.	Max.		
Drain-source on-state resistance	$R_{DS(on)}$	$I_D = 19.3 \text{ A}$	$T_{vj} = 25 \text{ }^\circ\text{C}$, $V_{GS(on)} = 18 \text{ V}$		39	54.4	mΩ
			$T_{vj} = 100 \text{ }^\circ\text{C}$, $V_{GS(on)} = 18 \text{ V}$		54		
			$T_{vj} = 175 \text{ }^\circ\text{C}$, $V_{GS(on)} = 18 \text{ V}$		77		
			$T_{vj} = 25 \text{ }^\circ\text{C}$, $V_{GS(on)} = 15 \text{ V}$		50.4	61.5	
Gate-source threshold voltage	$V_{GS(th)}$	$I_D = 10 \text{ mA}$, $V_{DS} = V_{GS}$ (tested after 1 ms pulse at $V_{GS} = 20 \text{ V}$)	$T_{vj} = 25 \text{ }^\circ\text{C}$	3.5	4.2	5.2	V
			$T_{vj} = 175 \text{ }^\circ\text{C}$		3.6		
Zero gate-voltage drain current	I_{DSS}	$V_{DS} = 1200 \text{ V}$, $V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ }^\circ\text{C}$			150	μA
			$T_{vj} = 175 \text{ }^\circ\text{C}$		2.6		
Gate leakage current	I_{GSS}	$V_{DS} = 0 \text{ V}$	$V_{GS} = 23 \text{ V}$			100	nA
			$V_{GS} = -10 \text{ V}$			-100	
Forward transconductance	g_{fs}	$I_D = 19.3 \text{ A}$, $V_{DS} = 20 \text{ V}$		12.9		S	
Internal gate resistance	$R_{G,int}$	$f = 1 \text{ MHz}$, $V_{AC} = 25 \text{ mV}$		2.5		Ω	
Input capacitance	C_{iss}	$V_{DD} = 800 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 100 \text{ kHz}$, $V_{AC} = 25 \text{ mV}$		1620		pF	
Output capacitance	C_{oss}	$V_{DD} = 800 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 100 \text{ kHz}$, $V_{AC} = 25 \text{ mV}$		75		pF	
Reverse transfer capacitance	C_{rss}	$V_{DD} = 800 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 100 \text{ kHz}$, $V_{AC} = 25 \text{ mV}$		11		pF	
C_{oss} stored energy	E_{oss}	$V_{DD} = 800 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 100 \text{ kHz}$, $V_{AC} = 25 \text{ mV}$		30		μJ	
Total gate charge	Q_G	$V_{DD} = 800 \text{ V}$, $I_D = 19.3 \text{ A}$, $V_{GS} = 0/18 \text{ V}$, turn-on pulse		51		nC	
Plateau gate charge	$Q_{GS(pl)}$	$V_{DD} = 800 \text{ V}$, $I_D = 19.3 \text{ A}$, $V_{GS} = 0/18 \text{ V}$, turn-on pulse		12.7		nC	
Gate-to-drain charge	Q_{GD}	$V_{DD} = 800 \text{ V}$, $I_D = 19.3 \text{ A}$, $V_{GS} = 0/18 \text{ V}$, turn-on pulse		10.2		nC	

(table continues...)

Table 4 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 800\text{ V}, I_D = 19.3\text{ A},$ $V_{GS} = 0/18\text{ V},$ $R_{GS(on)} = 2\ \Omega,$ $R_{GS(off)} = 2\ \Omega, L_\sigma = 15\text{ nH},$ diode: body diode at $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$		17	ns
			$T_{vj} = 175\text{ }^\circ\text{C}$		16	
Rise time	t_r	$V_{DD} = 800\text{ V}, I_D = 19.3\text{ A},$ $V_{GS} = 0/18\text{ V},$ $R_{GS(on)} = 2\ \Omega,$ $R_{GS(off)} = 2\ \Omega, L_\sigma = 15\text{ nH},$ diode: body diode at $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$		6.4	ns
			$T_{vj} = 175\text{ }^\circ\text{C}$		7.3	
Turn-off delay time	$t_{d(off)}$	$V_{DD} = 800\text{ V}, I_D = 19.3\text{ A},$ $V_{GS} = 0/18\text{ V},$ $R_{GS(on)} = 2\ \Omega,$ $R_{GS(off)} = 2\ \Omega, L_\sigma = 15\text{ nH},$ diode: body diode at $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$		20.6	ns
			$T_{vj} = 175\text{ }^\circ\text{C}$		21	
Fall time	t_f	$V_{DD} = 800\text{ V}, I_D = 19.3\text{ A},$ $V_{GS} = 0/18\text{ V},$ $R_{GS(on)} = 2\ \Omega,$ $R_{GS(off)} = 2\ \Omega, L_\sigma = 15\text{ nH},$ diode: body diode at $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$		6.9	ns
			$T_{vj} = 175\text{ }^\circ\text{C}$		6.9	
Turn-on energy	E_{on}	$V_{DD} = 800\text{ V}, I_D = 19.3\text{ A},$ $V_{GS} = 0/18\text{ V},$ $R_{GS(on)} = 2\ \Omega,$ $R_{GS(off)} = 2\ \Omega, L_\sigma = 15\text{ nH},$ diode: body diode at $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$		190	μJ
			$T_{vj} = 175\text{ }^\circ\text{C}$		305	
Turn-off energy	E_{off}	$V_{DD} = 800\text{ V}, I_D = 19.3\text{ A},$ $V_{GS} = 0/18\text{ V},$ $R_{GS(on)} = 2\ \Omega,$ $R_{GS(off)} = 2\ \Omega, L_\sigma = 15\text{ nH},$ diode: body diode at $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$		50	μJ
			$T_{vj} = 175\text{ }^\circ\text{C}$		53	
Total switching energy	E_{tot}	$V_{DD} = 800\text{ V}, I_D = 19.3\text{ A},$ $V_{GS} = 0/18\text{ V},$ $R_{GS(on)} = 2\ \Omega,$ $R_{GS(off)} = 2\ \Omega, L_\sigma = 15\text{ nH},$ diode: body diode at $V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$		270	μJ
			$T_{vj} = 175\text{ }^\circ\text{C}$		478	
Virtual junction temperature	T_{vj}			-55	175	$^\circ\text{C}$

3 Body diode (MOSFET)

Note: For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

The chip technology was characterized up to 200 kV/μs. The measured dv/dt was limited by measurement test setup and package.

Dynamic test circuit see Fig. F.

3 Body diode (MOSFET)

Table 5 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit	
Drain-source voltage	V_{DSS}	$T_{vj} \geq 25\text{ °C}$	1200	V	
Continuous reverse drain current for $R_{th(j-c,max)}$, limited by $T_{vj(max)}$	I_{SDC}	$V_{GS} = 0\text{ V}$	$T_c = 25\text{ °C}$	54	A
			$T_c = 100\text{ °C}$	33	
Peak reverse drain current, t_p limited by $T_{vj(max)}$	I_{SM}	$V_{GS} = 0\text{ V}$	117	A	

Table 6 Characteristic values

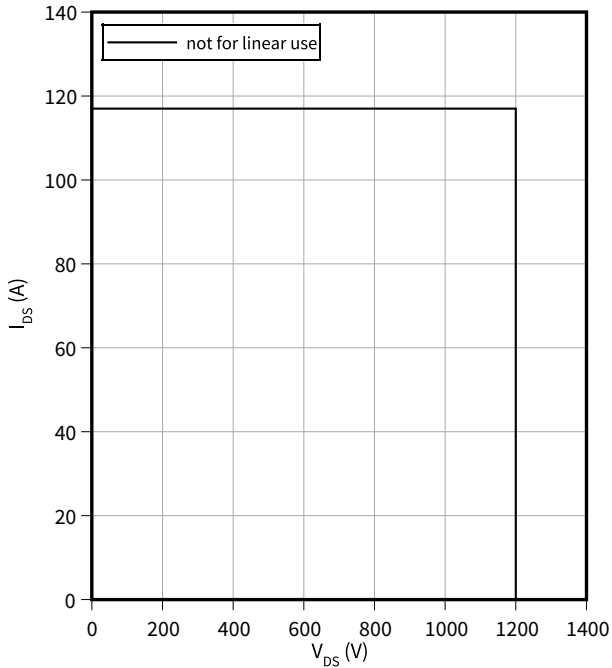
Parameter	Symbol	Note or test condition	Values			Unit	
			Min.	Typ.	Max.		
Drain-source reverse voltage	V_{SD}	$I_{SD} = 19.3\text{ A}, V_{GS} = 0\text{ V}$	$T_{vj} = 25\text{ °C}$		3.8	5	V
			$T_{vj} = 100\text{ °C}$		3.7		
			$T_{vj} = 175\text{ °C}$		3.6		
MOSFET forward recovery charge	Q_{fr}	$V_{DD} = 800\text{ V}, I_{SD} = 19.3\text{ A}, V_{GS} = 0\text{ V}, di_{SD}/dt = 3000\text{ A}/\mu\text{s}, Q_{fr}$ includes also Q_C	$T_{vj} = 25\text{ °C}$		160		nC
			$T_{vj} = 175\text{ °C}$		293		
MOSFET peak forward recovery current	I_{frm}	$V_{DD} = 800\text{ V}, I_{SD} = 19.3\text{ A}, V_{GS} = 0\text{ V}, di_{SD}/dt = 3000\text{ A}/\mu\text{s}, Q_{fr}$ includes also Q_C	$T_{vj} = 25\text{ °C}$		36		A
			$T_{vj} = 175\text{ °C}$		57		
MOSFET forward recovery energy	E_{fr}	$V_{DD} = 800\text{ V}, I_{SD} = 19.3\text{ A}, V_{GS} = 0\text{ V}, di_{SD}/dt = 3000\text{ A}/\mu\text{s}, Q_{fr}$ includes also Q_C	$T_{vj} = 25\text{ °C}$		30		μJ
			$T_{vj} = 175\text{ °C}$		120		
Virtual junction temperature	T_{vj}		-55		175	°C	

4 Characteristics diagrams

Reverse bias safe operating area (RBSOA)

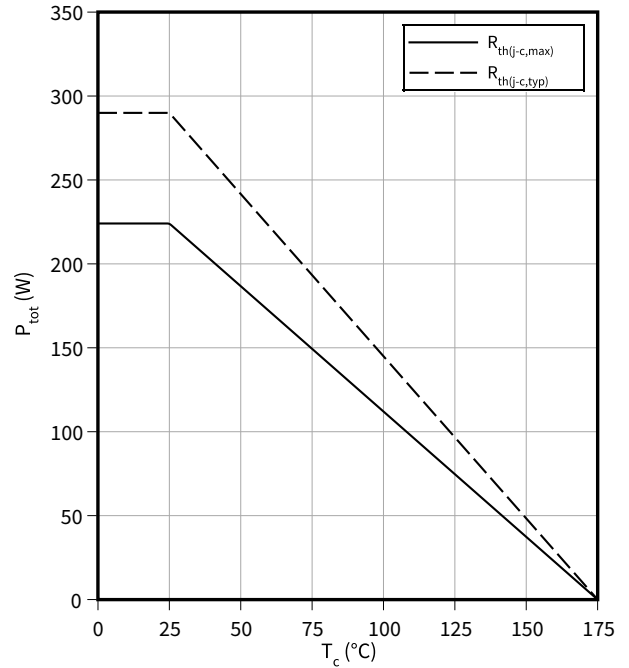
$$I_{DS} = f(V_{DS})$$

$$T_{vj} \leq 175\text{ °C}, V_{GS} = 0/18\text{ V}, T_c = 25\text{ °C}$$



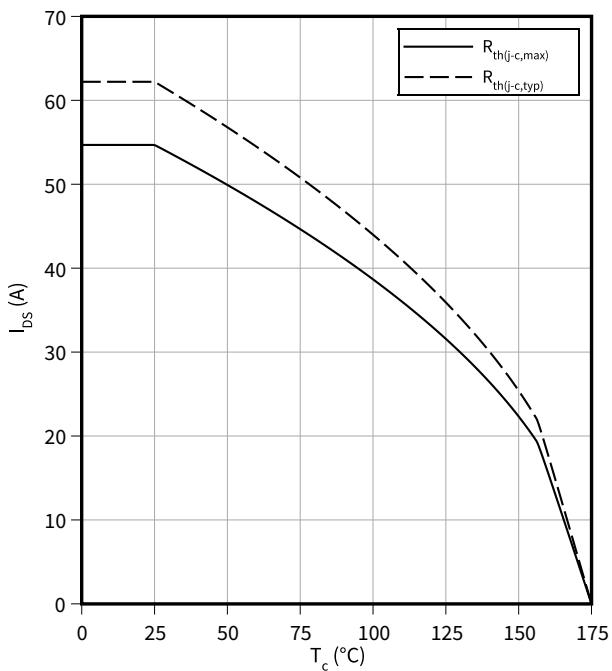
Power dissipation as a function of case temperature limited by bond wire

$$P_{tot} = f(T_c)$$



Maximum DC drain to source current as a function of case temperature limited by bond wire

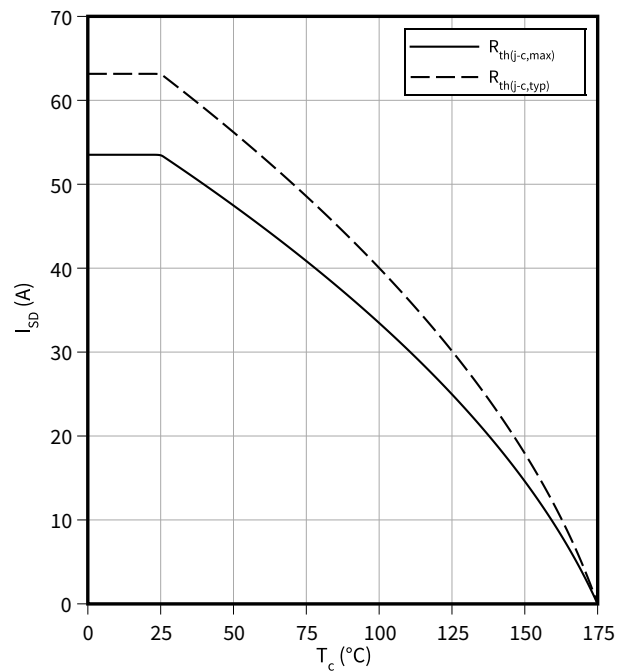
$$I_{DS} = f(T_c)$$



Maximum source to drain current as a function of case temperature limited by bond wire

$$I_{SD} = f(T_c)$$

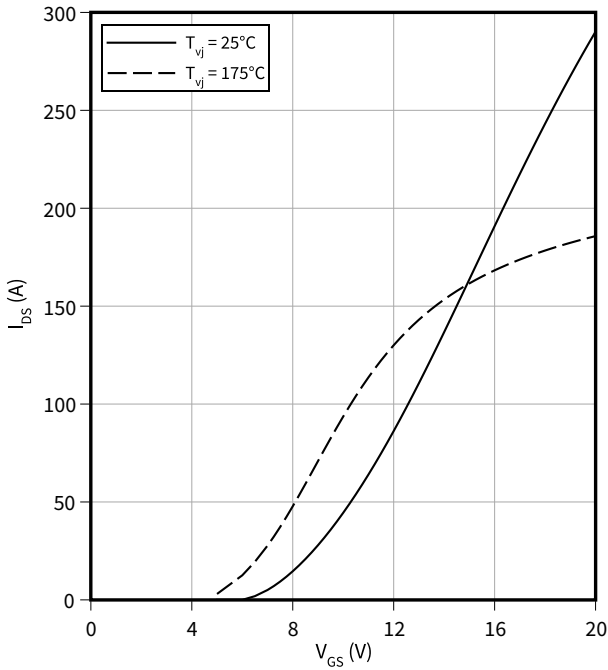
$$V_{GS} = 0\text{ V}$$



4 Characteristics diagrams

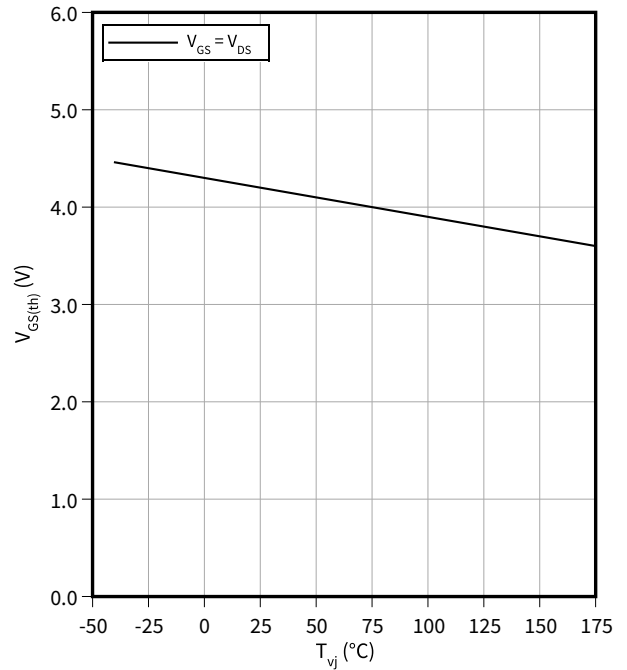
Typical transfer characteristic

$I_{DS} = f(V_{GS})$
 $V_{DS} = 20 \text{ V}$, $t_p = 20 \mu\text{s}$



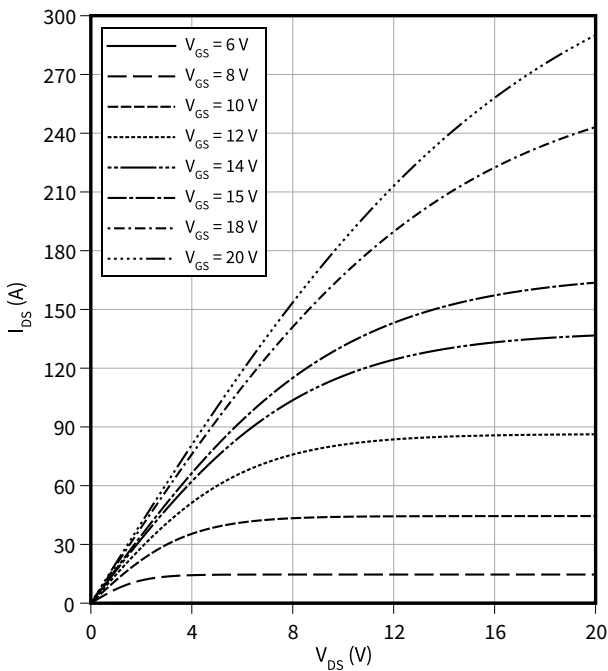
Typical gate-source threshold voltage as a function of junction temperature

$V_{GS(th)} = f(T_{vj})$
 $I_D = 8.3 \text{ mA}$



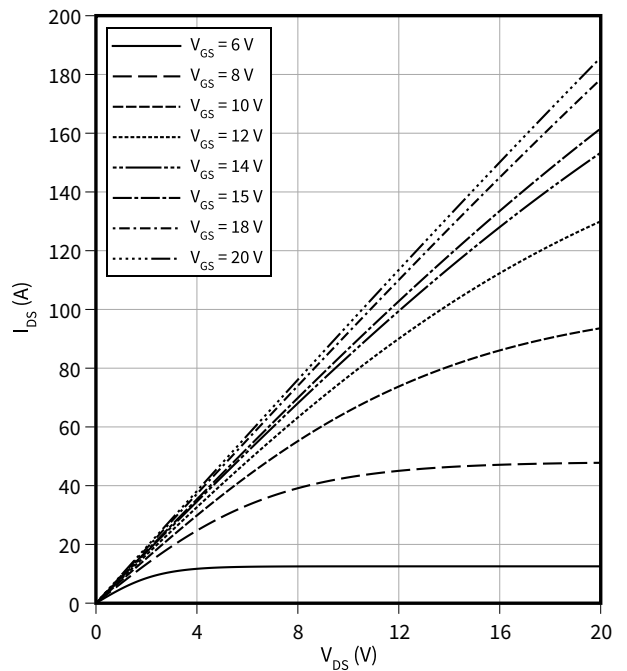
Typical output characteristic, V_{GS} as parameter

$I_{DS} = f(V_{DS})$
 $T_{vj} = 25^\circ\text{C}$, $t_p = 20 \mu\text{s}$



Typical output characteristic, V_{GS} as parameter

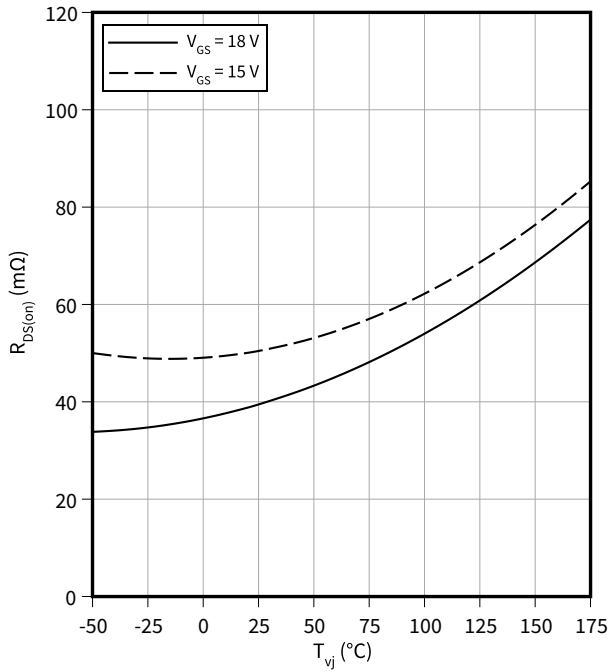
$I_{DS} = f(V_{DS})$
 $T_{vj} = 175^\circ\text{C}$, $t_p = 20 \mu\text{s}$



4 Characteristics diagrams

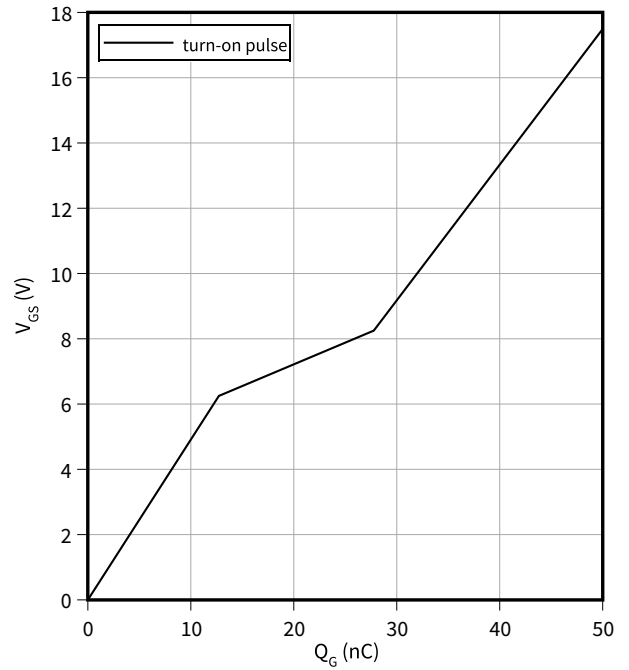
Typical on-state resistance as a function of junction temperature

$R_{DS(on)} = f(T_{vj})$
 $I_D = 19.3 \text{ A}$



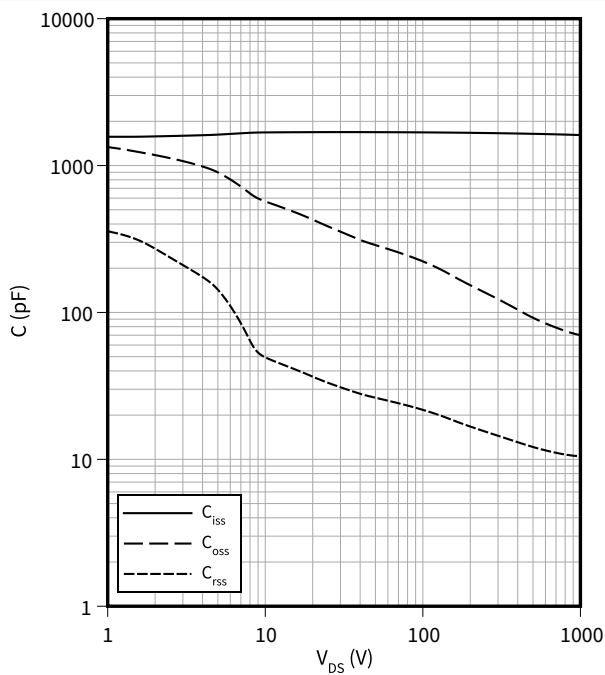
Typical gate charge

$V_{GS} = f(Q_G)$
 $I_D = 19.3 \text{ A}, V_{DS} = 800 \text{ V}$



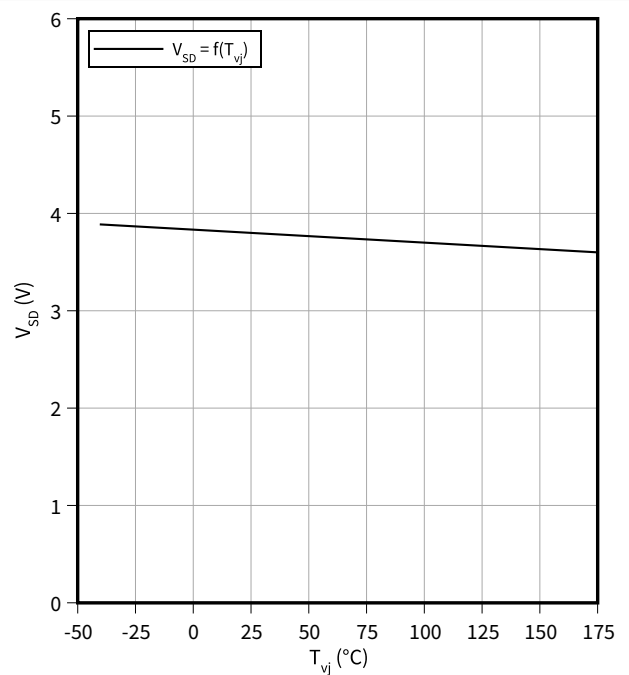
Typical capacitance as a function of drain-source voltage

$C = f(V_{DS})$
 $f = 100 \text{ kHz}, V_{GS} = 0 \text{ V}$



Typical reverse drain voltage as function of junction temperature

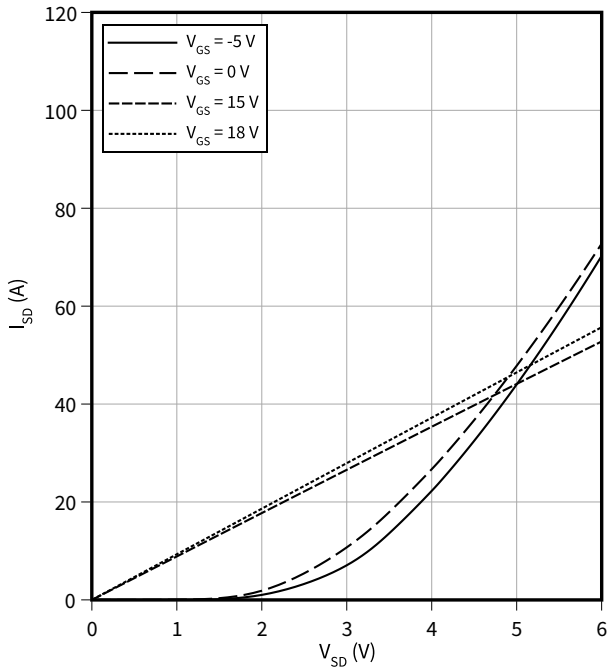
$V_{SD} = f(T_{vj})$
 $I_{SD} = 19.3 \text{ A}, V_{GS} = 0 \text{ V}$



4 Characteristics diagrams

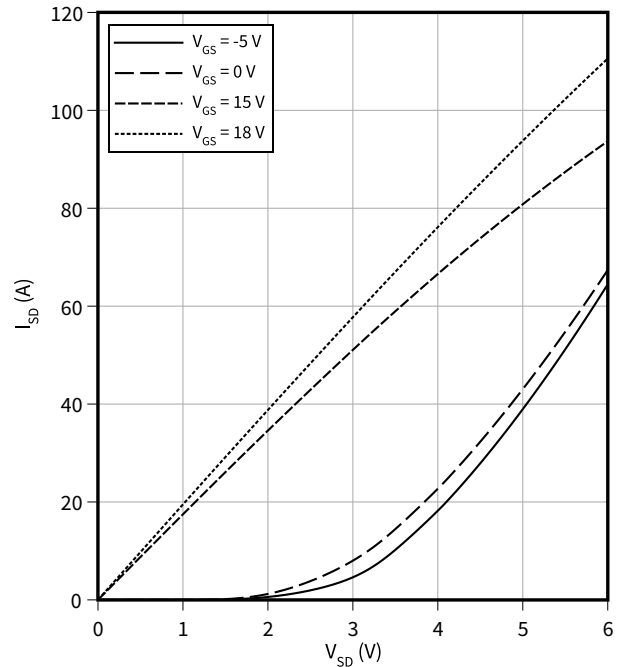
Typical reverse drain current as a function of reverse drain voltage, V_{GS} as parameter

$I_{SD} = f(V_{SD})$
 $T_{vj} = 175\text{ °C}$, $t_p = 20\text{ }\mu\text{s}$



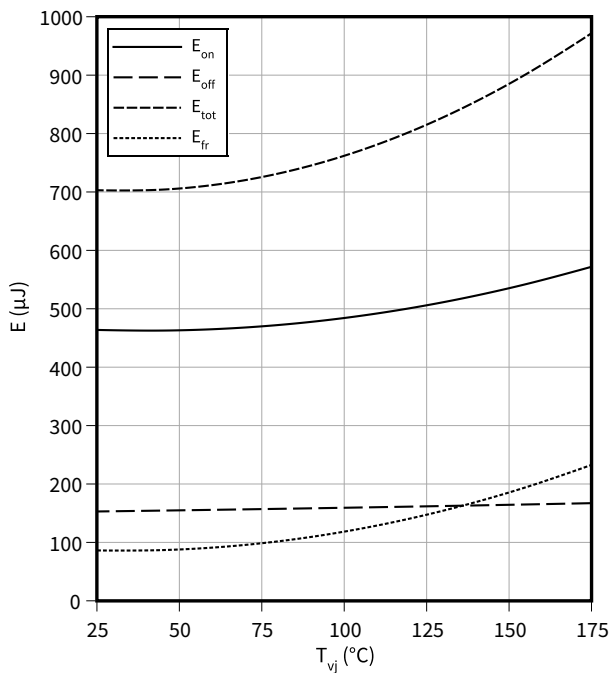
Typical reverse drain current as a function of reverse drain voltage, V_{GS} as parameter

$I_{SD} = f(V_{SD})$
 $T_{vj} = 25\text{ °C}$, $t_p = 20\text{ }\mu\text{s}$



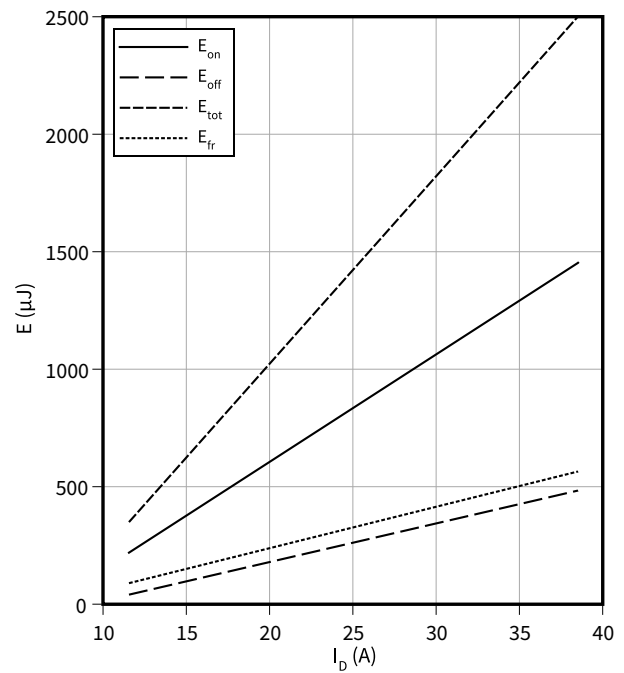
Typical switching energy as a function of junction temperature, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$E = f(T_{vj})$
 $V_{GS} = 0/18\text{ V}$, $I_D = 19.3\text{ A}$, $R_{G,ext} = 2\text{ }\Omega$, $V_{DD} = 800\text{ V}$



Typical switching energy as a function of drain current, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$E = f(I_D)$
 $V_{GS} = 0/18\text{ V}$, $T_{vj} = 175\text{ °C}$, $R_{G,ext} = 2\text{ }\Omega$, $V_{DD} = 800\text{ V}$

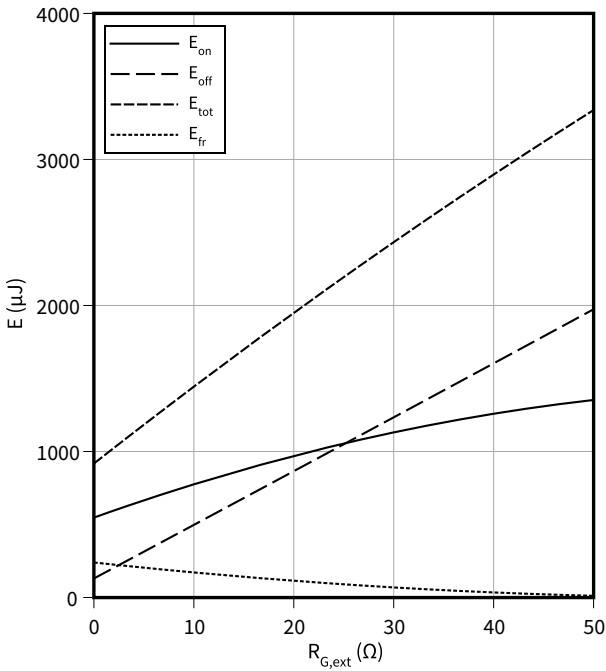


4 Characteristics diagrams

Typical switching energy losses as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$E = f(R_{G,ext})$

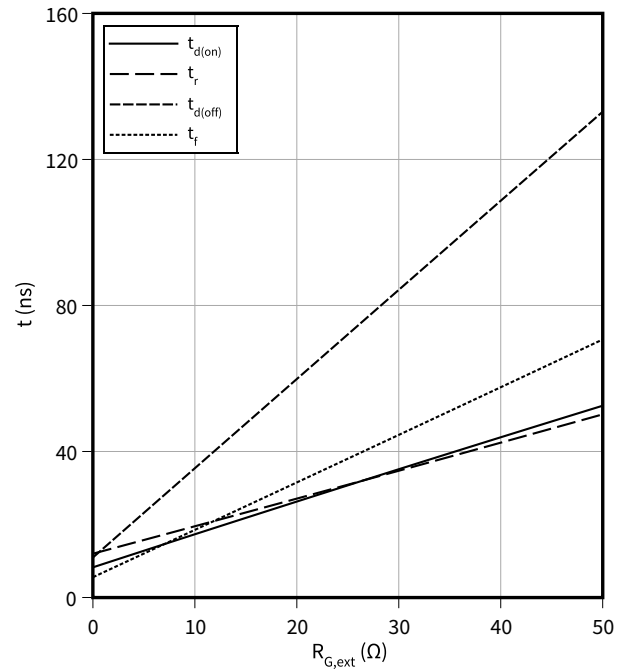
$V_{GS} = 0/18\text{ V}$, $I_D = 19.3\text{ A}$, $T_{vj} = \text{ }^\circ\text{C}$, $V_{DD} = 800\text{ V}$



Typical switching times as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$t = f(R_{G,ext})$

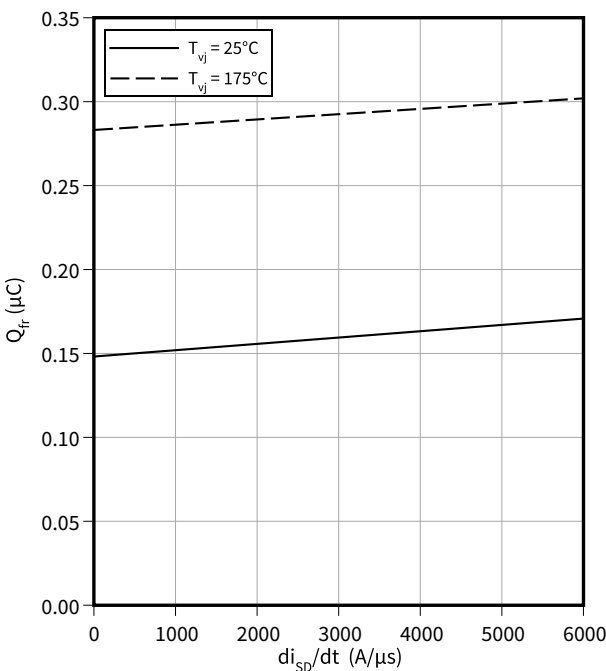
$I_D = 19.3\text{ A}$, $T_{vj} = 175\text{ }^\circ\text{C}$, $V_{DD} = 800\text{ V}$, $V_{GS} = 0/18\text{ V}$



Typical reverse recovery charge as a function of reverse drain current slope, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$Q_{fr} = f(di_{SD}/dt)$

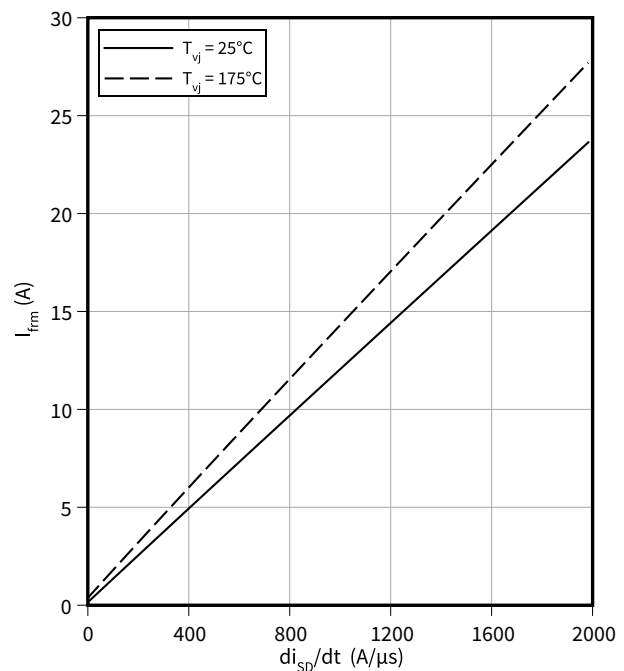
$V_{GS} = 0/18\text{ V}$, $I_{SD} = 19.3\text{ A}$, $V_{DD} = 800\text{ V}$



Typical reverse recovery current as a function of reverse drain current slope, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$I_{frm} = f(di_{SD}/dt)$

$V_{GS} = 0/18\text{ V}$, $I_{SD} = 19.3\text{ A}$, $V_{DD} = 800\text{ V}$

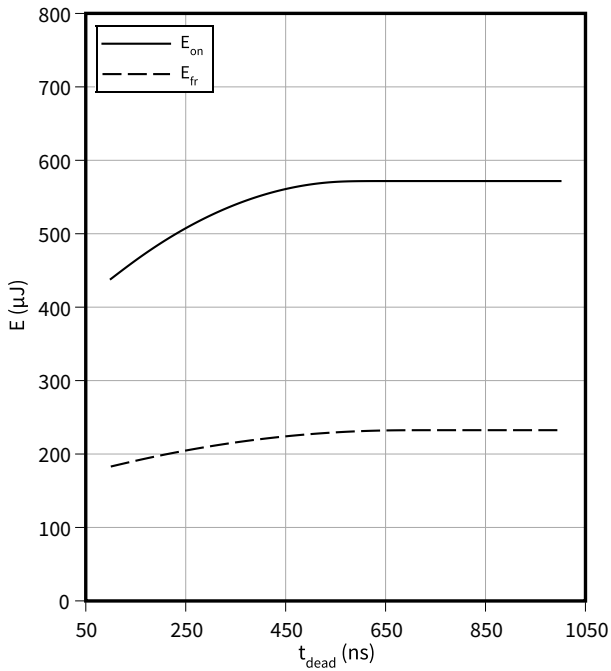


4 Characteristics diagrams

Typical switching energy losses as a function of dead time / blanking time, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = -5$ V

$$E = f(t_{dead})$$

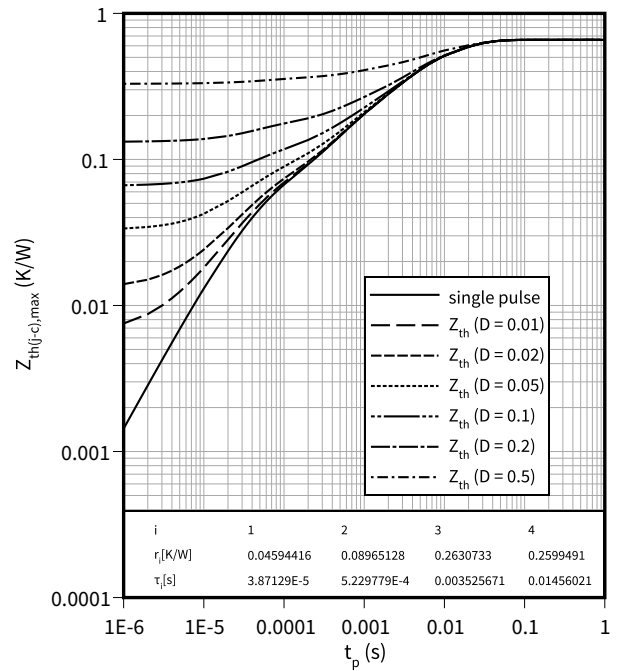
$V_{GS} = -5/18$ V, $I_D = 19.3$ A, $T_{vj} = 175$ °C, $V_{DD} = 800$ V



Max. transient thermal impedance (MOSFET/diode)

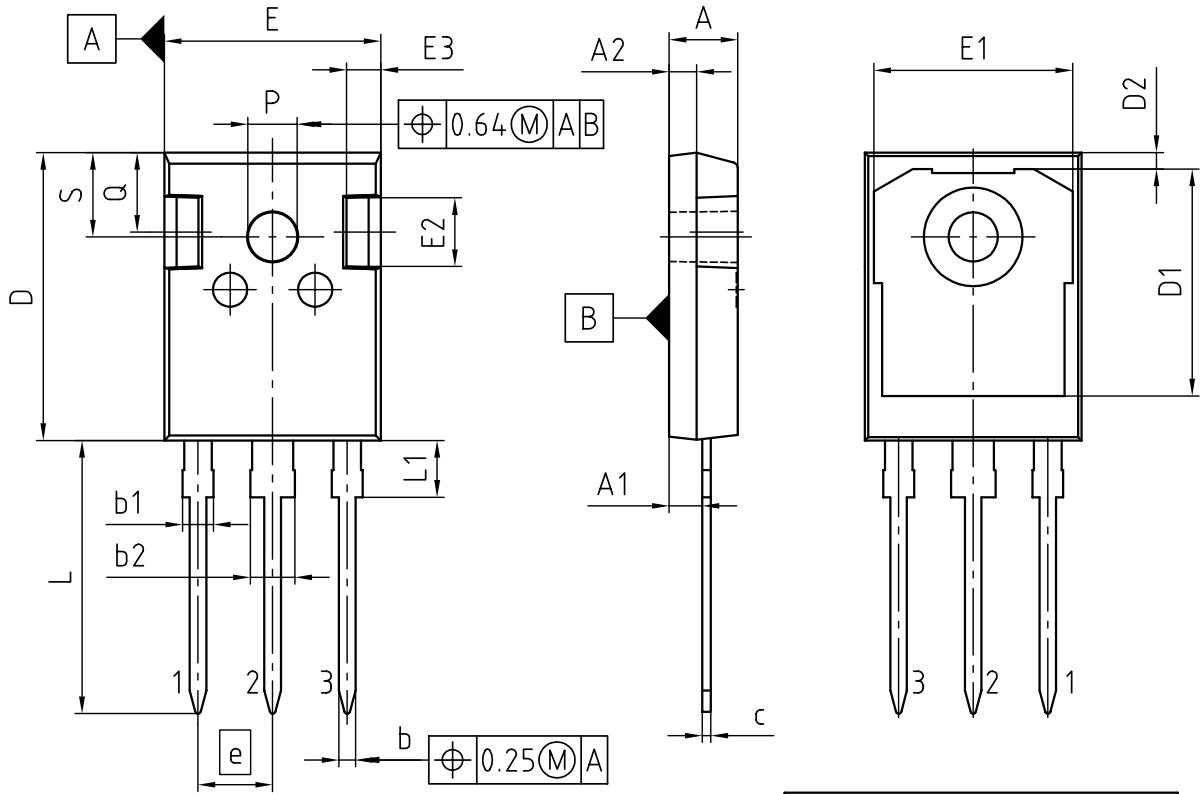
$$Z_{th(j-c),max} = f(t_p)$$

$$D = t_p/T$$



5 Package outlines

PG-TO247-3-STD-NN2.5



PACKAGE - GROUP NUMBER: PG-TO247-3-U06		
DIMENSIONS	MILLIMETERS	
	MIN.	MAX.
A	4.83	5.21
A1	2.27	2.54
A2	1.85	2.16
b	1.07	1.33
b1	1.90	2.41
b2	2.87	3.38
c	0.55	0.68
D	20.80	21.10
D1	16.25	17.65
D2	0.95	1.35
E	15.70	16.13
E1	13.10	14.15
E2	3.68	5.10
E3	1.00	2.60
e	5.44	
N	3	
L	19.80	20.32
L1	4.10	4.47
øP	3.50	3.70
Q	5.49	6.00
S	6.04	6.30

NOTE:
DIMENSIONS DO NOT INCLUDE MOLDFLASH; PROTRUSION OR GATE BURRS

Figure 1

6 Testing conditions

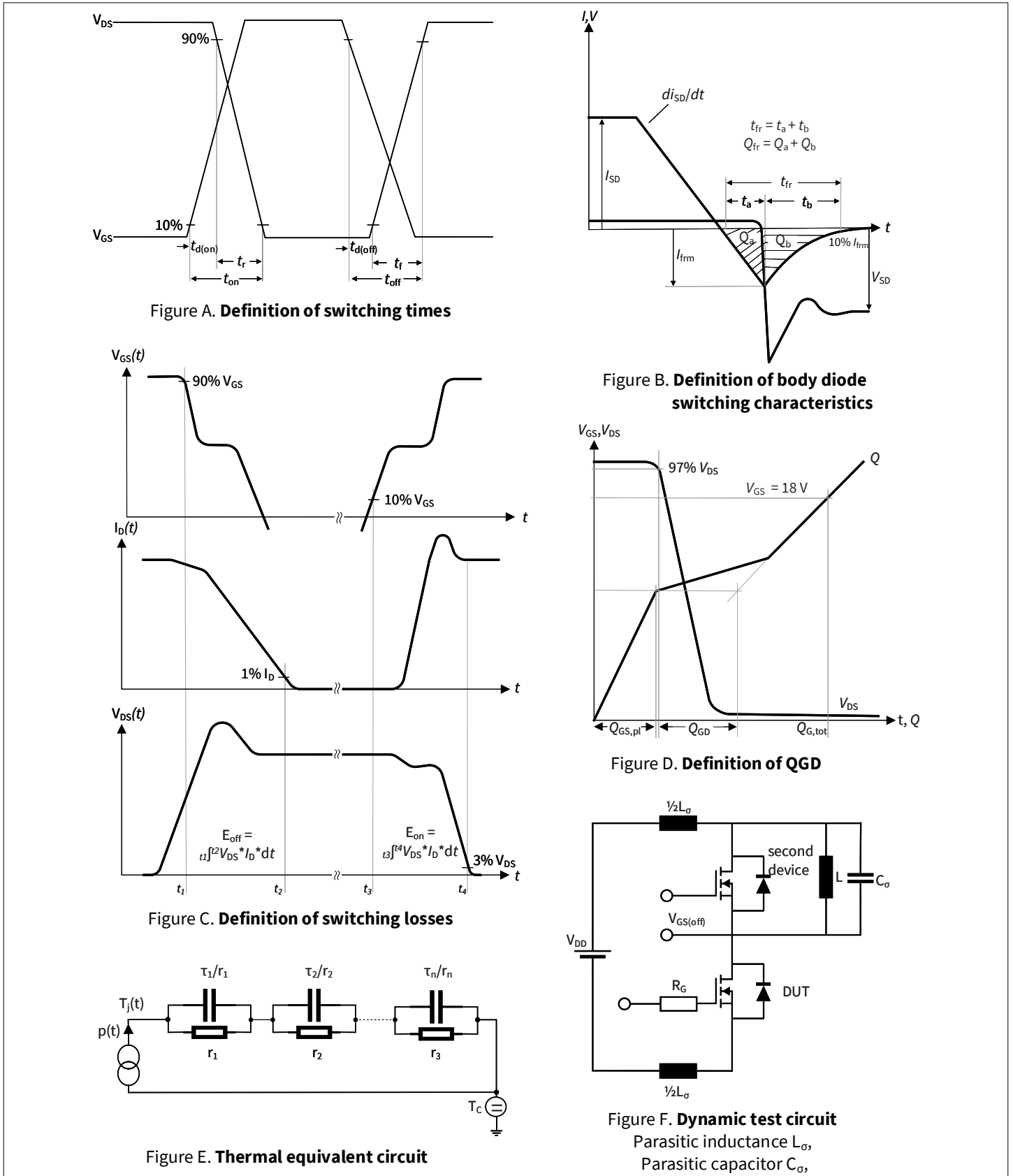


Figure 2

Revision history

Document revision	Date of release	Description of changes
1.00	2022-02-02	Final datasheet
1.10	2022-08-10	Change of test condition of dynamic capacitances in Table 4, "Characteristic values" (C_{iss} , C_{oss} , C_{rss}): $V_{DD} = 25\text{ V}$ to $V_{DD} = 800\text{ V}$ Correction of unit of "Input capacitance" C_{iss} from nF to pF Change of V_{GS} "Gate-source voltage, max. static voltage" in Table 2, "Maximum rated values" from -5/20 V to -7/20 V Editorial changes in "Features" on page 1 Editorial changes in "Package" on page 1 Correction of unit of x-axis at diagram "Max. transient thermal impedance (MOSFET/diode)" from μs to s, on page 13 Correction of diagram "Typical reverse drain current as a function of reverse drain voltage, V_{GS} as parameter", on page 11
1.20	2023-02-20	Correction of I_{DSS} in table 4 on page 4 Editorial changes
1.30	2023-05-08	Correction of gate charge values in Table 4

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